

IN THE CLAIMS:

Please cancel claims 10 through 18, without prejudice or disclaimer to the filing of a divisional application directed to the subject matter thereof.

Claims 2, 5, 6, 7, 8 and 9 have been amended herein, and new claims 19 through 22 added. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Original) A substrate for an electronic device configured for mounting a discrete conductive element thereon, the substrate comprising:
 - a sheet of insulative material;
 - a metal layer defining a terminal pad formed on a surface of the sheet;
 - an insulative mask extending over the sheet and having an aperture therein through which a portion of the terminal pad is exposed; and
 - a bond pad layer comprising at least another metal layer formed over, at most, a portion of the exposed portion of the terminal pad, the bond pad layer extending up a sidewall of the aperture and over a portion of the insulative mask adjacent to the aperture.
2. (Currently Amended) The substrate of claim 1, further comprising a solder ball in direct electrical contact with both the bond pad layer and the terminal pad.
3. (Original) The substrate of claim 2, wherein the solder ball is attached to a side surface of the bond pad layer.
4. (Original) The substrate of claim 3, wherein the solder ball is attached to the portion of the bond pad layer extending over the insulative mask.

5. (Currently Amended) The substrate of claim-21, wherein the bond pad layer is configured as radially extending elements generally symmetrically arranged about an exposed, central portion of the terminal pad.

6. (Currently Amended) The substrate of claim-21, wherein the bond pad layer comprises a plurality of apertures through which the terminal pad is exposed.

7. (Currently Amended) A substrate for an electronic device configured for mounting a discrete conductive element thereon, the substrate comprising:
a sheet of insulative material;
a metal layer defining a terminal pad formed on a surface of the sheet;
an insulative mask extending over the sheet and having an aperture therein through which a portion of the terminal pad is exposed, the exposed portion of the terminal pad having a centroid; and
a bond pad layer comprising at least a metal layer formed over at least a portion of the exposed portion of the terminal pad, extending up a sidewall of the aperture and over a portion of the insulative mask adjacent to the aperture, and having a centroid, the bond pad layer further comprising a plurality of apertures through which portions of the terminal pad are exposed;
~~wherein the centroid of the bond pad layer is misaligned with respect to the centroid of the terminal pad.~~

8. (Currently Amended) The substrate of claim 7, wherein ~~the~~ a centroid of the bond pad layer is positioned according to a measured lateral position of the aperture in the insulative mask.

9. (Currently Amended) The substrate of claim 7, wherein ~~misalignment between the centroid of the bond pad layer~~ is selectively configured for positioning of a solder ball thereover ~~and the centroid of the terminal pad is attributable to removal of a portion of the bond pad layer~~ an initially disposed portion thereof.

Claims 10 through 18 (Canceled).

19. (New) The substrate of claim 7, further comprising a solder ball in direct electrical contact with both the bond pad layer and the terminal pad.

20. (New) The substrate of claim 19, wherein the solder ball is attached to a side surface of the bond pad layer.

21. (New) The substrate of claim 20, wherein the solder ball is attached to the portion of the bond pad layer extending over the insulative mask.

22. (New) The substrate of claim 7, wherein the bond pad layer is configured as radially extending elements generally symmetrically arranged with respect to an exposed, central portion of the terminal pad.